In the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Cancelled)

2. (Currently Amended) The ~~compound~~ component of claim 4, wherein the electrical component is a substrate having an electrical circuit formed on at least one surface of the substrate and at least one semi-conductor chip electrically connected to the electrical circuit.

3. (Cancelled)

4. (Currently Amended) An encapsulated, overmolded and/or underfilled electrical component, comprising:

an electrical component encapsulated, overmolded and/or underfilled with a polymeric composite including a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces, the inorganic filler particle content being 20 percent or less by weight based on the weight of the polymeric composite.

5. (Currently Amended) The component of claim 4, wherein the inorganic filler particle content is 15 percent or less by weight based on the weight of the polymeric composite.

6. (Currently Amended) The component of claim 4, wherein the inorganic filler particle is a smectite clay mineral.

7. (Original) The component of claim 6, wherein the smectite clay mineral is montmorillonite.

8. (Currently Amended) The component of claim 4, wherein the synthetic resin matrix is a thermoset resin.

9. (Original) The component of claim 8, wherein the thermoset resin is selected from epoxy, phenolic, polyurethane and polyurea resins.

10. (Currently Amended) The component of claim 4, wherein the synthetic resin matrix is a thermoplastic resin.

11. (Original) The component of claim 10, wherein the thermoplastic resin is selected from polyamides, copolyamides, polycarbonates, polyesters and copolyesters.

12. (Currently Amended) The component of claim 4, wherein the polymeric composite has a CTE from about 5 to 20 ppm/°C.

13. (Original) An encapsulated, overmolded and/or underfilled electrical component, comprising:

an electrical component encapsulated, overmolded and/or underfilled with a polymeric composite including a thermoplastic resin matrix and an inorganic particulate filler.

14. (Original) The component of claim 13, wherein the electrical component is a substrate having an electrical circuit formed on at least one surface of the substrate and at least one semi-conductor chip electrically connected to the electrical circuit.

15. (Cancelled)

16. (Currently Amended) The component of claim 13, wherein the inorganic particulate filler content is 20 percent or less by weight based on the weight of the polymeric composite.

17. (Currently Amended) The component of claim 13, wherein the inorganic particulate filler content is 15 percent or less by weight based on the weight of the polymeric composite.

18. (Currently Amended) The component of claim 13, wherein the inorganic particulate filler is a smectite clay mineral.

19. (Original) The component of claim 18, wherein the smectite clay mineral is montmorillonite.

20. (Currently Amended) The component of claim 13, wherein the thermoplastic resin matrix comprises a resin ~~is~~ selected from the group consisting of polyamides, copolyamides, polyesters, copolyesters and polycarbonates.

21. (Original) The component of claim 13, wherein the inorganic particulate filler is glass spheres.

22. (Original) The component of claim 21, wherein the glass spheres have an average diameter of from about 1 micrometer to about 50 micrometers.

23. (Canceled)

24. (New) An encapsulated, overmolded and/or underfilled electrical component, comprising:

a substrate having an electrical circuit;

a semi-conductor chip electrically connected to the substrate, the semi-conductor chip being spaced from the substrate by a distance of from about 10 micrometers to about 150 micrometers;

the component being completely encased within a polymer composite, the semi-conductor chip being completely encased by the substrate and a polymer composite, and/or the

space defined between the semi-conductor chip and the substrate being filled with a polymer composite;

wherein the polymer composite includes a synthetic resin matrix and inorganic filler particles substantially uniformly distributed in the synthetic resin matrix, the inorganic filler particles having a platelet structure defined by opposite substantially flat and substantially parallel faces, the inorganic filler particle content being 20% or less by weight based on the weight of the polymer composite.